



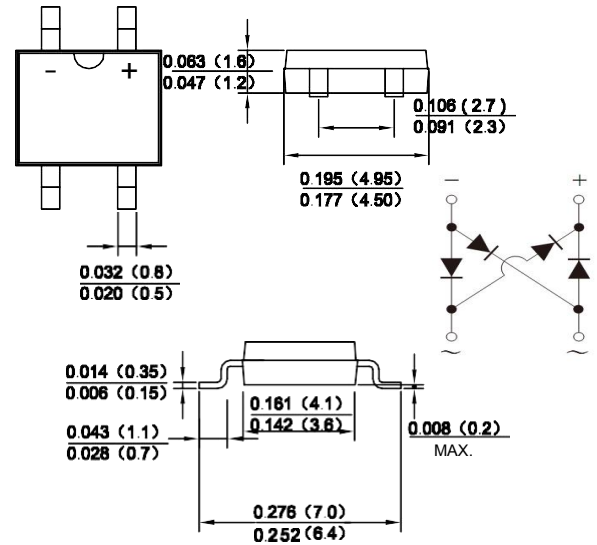
### Features

- Schottky Brrier Chip
- Low Power Loss,High Efficiency
- Ideally Suited for Automatic Assembly
- Surge Overload Rating to 30A Peak
- Plastic Case Material has UL Flammability Classification Rating 94V-0

### Mechanical Data

- Case: MB-F, molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Marking: type number
- Lead Free: For RoHS / Lead Free Version,

### MBF



dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	KMB 12F	KMB 13F	KMB 14F	KMB 145F	KMB 15F	KMB 16F	KMB 18F	KMB 110F	KMB 115F	KMB 120F	KMB 125F	UNITS	
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	20	30	40	45	50	60	80	100	150	200	250		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	31	35	42	56	70	105	140	175	V	
DC Blocking Voltage	V <sub>DC</sub>	20	30	40	45	50	60	80	100	150	200	250		
Average Rectified Output Current ( Note1) @T <sub>c</sub> = 100°C	I <sub>F(AV)</sub>	1.0											A	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30											A	
I <sup>2</sup> t Rating for Fusing (t < 8.3ms)	I <sup>2</sup> t	3.735											A <sup>2</sup> s	
Forward Voltage per element @I <sub>F</sub> = 1.0A	V <sub>FM</sub>	0.55			0.7			0.85		0.90		0.92	V	
Peak Reverse Current @T <sub>J</sub> = 25°C At Rated DC Blocking Voltage @T <sub>J</sub> = 100°C	I <sub>RM</sub>	0.1						0.05						mA
		10						5						
Typical Junction Capacitance ( Note2)	C <sub>j</sub>	50						35						pF
Typical Thermal Resistance	R <sub>θJL</sub>	16											°C/W	
Operating junction temperature range	T <sub>J</sub>	-55 to +150											°C	
Operating and Storage Temperature Range	T <sub>STG</sub>	-55 to +150											°C	

**Note:**

1. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.



FIG. 1- FORWARD CURRENT DERATING CURVE

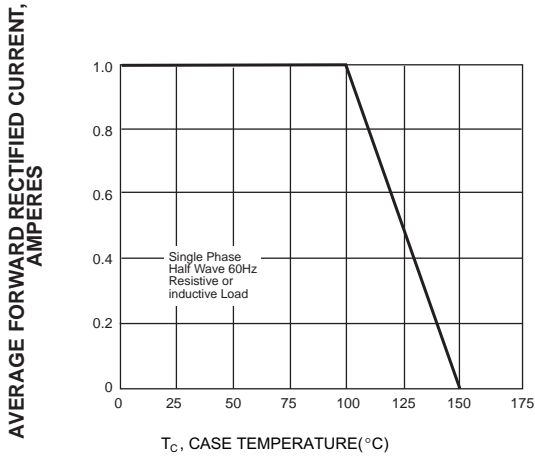


FIG. 2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

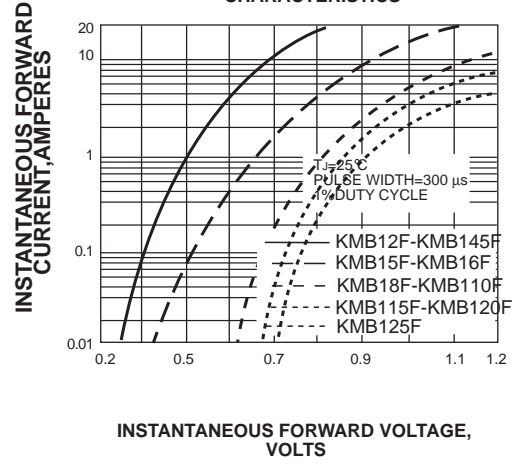


FIG. 3-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

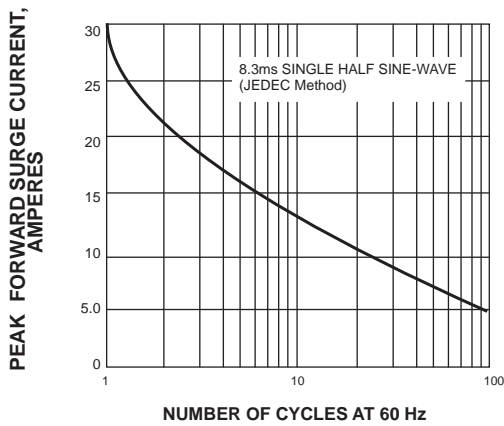


Fig 4 Typical Junction Capacitance

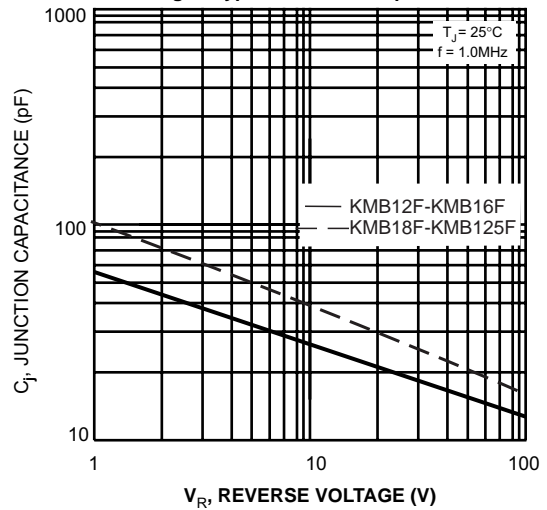


Fig. 5 Typical Reverse Characteristics

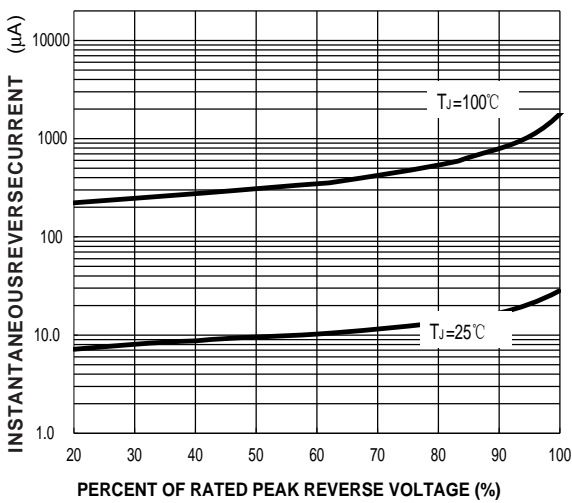


FIG.6 MOUNTING PAD LAYOUT

